L Number	Hits	Search Text	DB	Time stamp
1	13	((power ground) adj line) near5 width near5 (signal adj line)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 12:55
2	5974	(bump ball) and ((flat horizontal inclination) adj portion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 12:57
3	3240	(bump ball) and ((flat horizontal inclination) adj portion) and angle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 13:00
4	312	(bump ball) and ((flat horizontal inclination) adj portion) and angle and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 13:09
5	3	(bump ball) and (inclinat$4 adj portion) and angle and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 13:11
6	33	(bump ball) and (inclinat$4 adj portion) and angle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 13:13
7	1780	257/737-738.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 13:29
8	2	("6425516").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 13:26
9	16	("4754912" | "5488200" | "5600180" | "5604379" | "5731229" | "5777391" | "5811351" | "5897337" | "5989982" | "6063646" | "6118179" | "6168972" | "6171887" | "6180504" | "6181569" | "6260264").PN.	USPAT	2003/01/24 13:26
10	16	("4754912" | "5488200" | "5600180" | "5604379" | "5731229" | "5777391" | "5811351" | "5897337" | "5989982" | "6063646" | "6118179" | "6168972" | "6171887" | "6180504" | "6181569" | "6260264").PN.	USPAT	2003/01/24 13:27
11	0	6425516.URPN.	USPAT	2003/01/24 13:27
12	0	electrically adj insulating adj contains adj particles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 13:30
13	1	insulating adj contains adj particles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 13:30
14	3876	insulating near2 particles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 13:31

15	103	(insulating adj layer) near1 particles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 15:04
16	2	("6376100").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 13:39
17	3	"6168872"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 15:18
18	2	("6456100").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 15:18
19	89	257/737-738,781,780,784,668,701.ccls. and (ball bump) and inclin$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 16:16
20	4	(("6313532") or ("6323439")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 16:17
-	2	("6037662").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 14:48
-	56	257/777-783,737-738.ccls. and (bump ball external) with (micrometer m)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 17:59
-	2	("6313532").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 14:54
-	5	("5327013" | "5567981" | "5900674" | "6097087" | "6111317").PN.	USPAT	2003/01/23 15:08
-	17	257/777-783,737-738.ccls. and wiring near5 (copper Cu) near5 (nickel Ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 15:10
-	804	257/777-783,737-738.ccls. and (Cu copper) near5 (nickel Ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 18:00
-	693	257/777-783,737-738.ccls. and (Cu copper) near3 (nickel Ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 18:10
-	589	257/777-783,737-738.ccls. and (Cu copper) near2 (nickel Ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 18:01

-		2	257/777-783,737-738.ccls. and wiring near2 (Cu copper) near2 (nickel Ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 18:02
-		24	wiring with ((Cu copper) adj layer) near3 ((nickel Ni) adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 19:42
-		118	257/777-783,737-738,734,759,773,787,792-793.ccls. and (ball bump) and inclin$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 15:38
-		0	wiring with ((Cu copper) adj layer) near3 ((nickel Ni) adj layer) and particle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 19:43
-		35	((Cu copper) adj layer) near3 ((nickel Ni) adj layer) and particle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 19:46
-		18	((Cu copper) adj layer) near5 ((nickel Ni) adj layer) and insulat$4 with (particle$1 filler)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 19:51
-		3	((Cu copper) adj layer) near5 ((nickel Ni) adj layer) and insulat$4 near5 contain near5 (particle$1 filler)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 19:54
-		9	((insulating dielectric) adj layer) near3 contain near3 particles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 12:11